



Advanced and Multifunctional Flexible Electronic Materials and Devices

Guest Editor:

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Deadline for manuscript submissions:

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Message from the Guest Editor

There has been a huge rise in research of flexible electronics, both of materials and applications. There is a clear indication of flexible electronic technologies being commercialized. This Special Issue aims to publish high-quality research papers focusing on flexible electronic materials and devices. Devices include, but are not limited to, sensors, photodetectors, diodes, transistors, memristors, antennas, solar cells, etc. The device should demonstrate an application towards flexible/wearable electronics, which include healthcare, security, flexible circuits, etc. Furthermore, large area deposition and the large-scale production of materials for flexible electronics are also of interest for this Special Issue. For this Special Issue, the submission of original papers, reviewer articles, and short communications is encouraged.





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Editor-in-Chief

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Message from the Editor-in-Chief

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